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PTO/SB/21 (12-97)

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TRANSMITTAL FORM (to be used for all correspondence after initial filing) BOX: NON-FEE AMENDMENT Express Mail Receipt No.	Application / Conf. No.	09/879,875 / 4969
	Filing Date	June 11, 2001
	First Named Inventor	Abu K. Eghan
	Examiner Name	V. Bhagawan
	Group Art Unit	2829
	Issue Fee Batch No.	
	Attorney Docket Number	X-901 US

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ENCLOSURES (check all that apply)		
<input type="checkbox"/> Fee Transmittal Form <input checked="" type="checkbox"/> Amendment / Response <input type="checkbox"/> Preliminary Amendment <input type="checkbox"/> After Final <input type="checkbox"/> Affidavit(s)/declaration(s) <input type="checkbox"/> Extension of Time Request <input type="checkbox"/> Change Status to LARGE ENTITY <input type="checkbox"/> Express Abandonment Request <input type="checkbox"/> Information Disclosure Statement <input type="checkbox"/> Substitute PTO-1449(s) IDS by Applicant (PTO/SB/08A) <input type="checkbox"/> Certified Copy of Priority Document(s) <input type="checkbox"/> Response to Missing Parts/ Incomplete Application <input type="checkbox"/> Response to Missing Parts under 37 CFR 1.52 or 1.53	<input type="checkbox"/> Assignment Papers (with Recordation Cover Sheet) <input type="checkbox"/> Declaration / Oath <input type="checkbox"/> Drawing(s) <input type="checkbox"/> Licensing-related Papers <input type="checkbox"/> Petition - <input type="checkbox"/> To Convert a Provisional Application <input type="checkbox"/> Power of Attorney, Revocation Change of Correspondence Address <input type="checkbox"/> Terminal Disclaimer <input type="checkbox"/> Request for Refund	<input type="checkbox"/> After Allowance Communication to <input type="checkbox"/> Appeal Communication to Board of Appeals and Interferences <input type="checkbox"/> Appeal Communication to Group (Appeal Notice, Brief, Reply Brief) <input type="checkbox"/> Status Letter <input checked="" type="checkbox"/> Return Receipt Postcard <input type="checkbox"/> Additional Enclosure(s) (please identify below): <div style="border: 1px solid black; height: 50px; width: 100%;"></div>
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Date	April 29, 2002	Charge any additional fees required/credit any overpayment to our Deposit Account Number: 24-0040

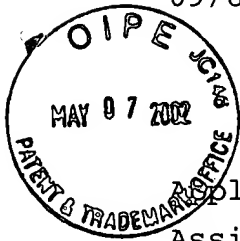
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09/879,875

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PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Abu K. Eghan et al.
Assignee: Xilinx, Inc.
Title: High Performance Flipchip Package That
Incorporates Heat Removal With Minimal Thermal
Mismatch
Serial No.: 09/879,875 File Date: 6/11/2002
Examiner: Venkatesha Bhagawan Art Unit: 2829
Docket No.: X-901 US

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Box Non-Fee Amendment
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Washington, D. C. 20231

AMENDMENT IN RESPONSE TO FIRST OFFICE ACTION

Dear Sir:

In response to the First Office Action mailed from the Patent Office on January 30, 2002, please replace the abstract and the following claims as indicated.

IN THE ABSTRACT

Please replace the Abstract with the following:

A semiconductor flipchip package includes a central cavity area on the first major side for receiving a flipchip die therein. The package substrate is substantially made from a single material that serves as the support and stiffener and provides within the cavity floor all the connecting points for flipchip interconnection to the silicon die. The integral cavity wall serves as a stiffener member of the package and provides the required mechanical stability of the whole arrangement without the need for a separate stiffener material to be adhesively attached. The cavity walls may contain extra routing metallization to create bypass capacitors to enhance electrical